

IN THE SPECIFICATION

Please amend the paragraph starting at page 22, line 30 as follows:

In the next step (Block 128), the input/output contact pads 80 on the die 62 are connected to the wire bond pads 72 on the lead frame 65. This may be accomplished using one of the known wire bonding methods, preferably ultrasonic aluminum (Block ~~103~~ 132) or thermosonic gold (Block 130) wire bonding techniques.

Please amend the paragraph starting at page 23, line 14 as follows:

For smaller IC packages without vertical walls, the encapsulation material can be removed over the entire top surface 184 of the package 160. The encapsulant 182 may then be placed over, or “blobbed”, on top of the mounted die 162, the die attach pad 164, the wire bonds 166 and the wire bond pads 172. The wire bond pads 172 are connected to lead frames 165. The encapsulant 182 can be easily formulated to have a viscosity such that the die 162 and wire bonds 166 are sufficiently protected. Because the encapsulant is nonconductive, even if the encapsulant runs over the edges of the package, the device will still be functional. While the package may not have precisely the same outline as a custom built device, the objectives of the packaging technique are still met. Further, after the “blob” on top and around the edges of the IC packages has cured, it can be trimmed or cut using conventional techniques to give the package a form factor shape that at least approximates the original IC package form shape.